

## REMARKS

In the Office Action of October 29, 2004, claims 31 and 32 were rejected under 35 U.S.C. §112, first paragraph as containing subject matter not described in the specification and under 35 U.S.C. §112, second paragraph, as being indefinite. The claims were also rejected under 35 U.S.C. §102(e) as anticipated by Degani, et al. (USP 6,074,897).

In response, claim 31 has been revised to recite the formation of a channel extending through an intermediate mounting substrate and a chip carrier to a gap between a semiconductor device and the chip carrier. This is believed to be an accurate description of channel 560 and its relation to chip carrier 524 and mounting substrate 540. Accordingly, the rejection of the claims on 35 U.S.C. §112, first and second paragraphs is believed to be overcome.

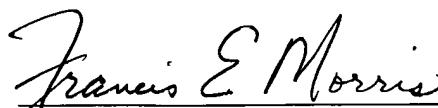
With respect to the rejection under 35 U.S.C. §102(e), Degani, et al. does not disclose or suggest the use of an intermediate mounting substrate in a semiconductor package or the provision of a channel through such substrate through which underfill material may be injected into a gap between the semiconductor and the chip carrier on which it is mounted.

Dependent claim 32 and newly added dependent claims 33-35 are believed patentable for the same reason claim 31 is patentable.

In view of the forgoing remarks, the claims in this application are believed to be in condition for allowance. Such action is respectfully requested. If the Examiner believes a telephone interview would expedite prosecution of this application, he is invited to call applicants' attorney at the number given below. No additional fee is believed due for filing this response. However, if a fee is due, please charge such fee to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310.

Respectfully submitted,

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